ABSTRACT OF THE DISCLOSURE

The present invention provides a semiconductor package allowing a semiconductor chip to be operated accurately and with high stability over a long period by effectively transferring the heat generated during the operation of the semiconductor chip to a heat sink. A package for housing a semiconductor chip comprises a substrate 2 having on the upper surface thereof a mounting space where a semiconductor chip 1 is to be mounted, a frame 3 being provided so as to surround the mounting space on the upper surface of the substrate 2 and having a joint 3a for an input/output terminal 5 on the side, and an input/output terminal 5 connected to the joint 3a, wherein the substrate 2, or part of the substrate 2, or the substrate 2 and the frame 3, or part of the substrate and the frame is formed from a metal-diamond composite in which a matrix material having diamond particles joined via a metal carbide is infiltrated with a copper and/or silver or a metal-diamond sintered body composed of diamond particles and copper. Further, the surface of the metal-diamond composite is plated with gold.